

## 2021.10.4 New Products Release

### **Sales Release of “Solder Ball Mounter for Wafer” having realized Higher Yield and Throughput**

We, AIMECHATEC, Ltd. (Head Office: Koyodai, Ryugasaki-shi, Ibaraki-pref. President: Isao Abe) are pleased to announce that “Solder Ball Mounting System for Wafer” will be released as our new proposal for Semiconductor Business.

This equipment has realized Higher Yield by applying our Solder Ball Mounting Technology for Semiconductor Package Substrate cultivated for many years. Moreover, this equipment has greatly improved Productivity and Material Use Efficiency for High Volume Manufacturing by mounting Higher Throughput New Squeegee Head. We will propose Total System Solution with Inspection & Repair Equipment for Wafer.

Solder Ball Mounting Process for Whole Surface Wafer has been adopted for Advanced Semiconductor Package such as FOWLP (Fan Out Wafer Level Package), WLCSP (Wafer Level Chip Size Package), etc. which are largely used in Mobile Devices. This equipment and system process can contribute greatly to Productivity Improvement compared with Solder Ball Mounting after Wafer Dicing Process. At present, this equipment is considered to be adopted in the industry in accordance with further requirements for Higher Yield and Throughput.

We will continue to contribute to safe and affluent society development through our technological innovations for manufacturing processes.

Contact:

AIMECHATEC, Ltd.

Sales Dept. TEL:0297-62-9119

<https://www.ai-mech.com/wp/en/newproducts/>



**Solder Ball Mounter for Wafer**